Package outline drawing:

OMP-780-4F-1

| Tolerances unless otherwise stated: <br> Dimension: $\pm 0.05$$\quad$ Angle: $\pm 1^{\circ}$ |  | Revision: | 0 |
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| Revision date: | $3 / 1 / 2018$ |  |  |
|  |  |  |  |
|  | Third angle projection | Sheet 1 of 2 |  |


| Drawing Notes |  |
| :---: | :---: |
| Items | Description |
| (1) | Dimensions are excluding mold protrusion. All areas located adjacent to the leads have a maximum mold protrusion of 0.25 mm (per side) and max. 0.62 mm in length. <br> At all other areas the mold protrusion is maximum 0.15 mm per side. See also detail $B$. |
| (2) | The metal protrusion (tie bars) in the corner will not stick out of the molding compound protrusions (detail A ). |
| (3) | The lead dambar (metal) protrusions are not included. Add 0.14 mm max to the total lead dimension at the dambar location. |
| (4) | The lead coplanarity over all leads is 0.1 mm maximum. |
| (5) | Dimension is measured 0.5 mm from the edge of the top package body. |
| (6) | The hatched area indicates the exposed metal heatsink. |
| (7) | The leads and exposed heatsink are plated with matte Tin (Sn). |




